g GE Energy		Functional Testing Specification
Parts & Repai Louisville, KY		LOU-GED-IS200RCSAG1A

Test Procedure for a IS200RCSAG1A Snubber Card

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DATE 8/29/16	DATE	DATE	DATE 8/29/20016

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1. SCOPE

1.1 This is a functional testing procedure for an IS200RCSAG1A Snubber Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
 - **3.1.1** Check board's electronic folder for more information

4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
- **4.2** Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken, cracked, or loosely connected
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - 4.2.1.3 Components visually damaged
 - 4.2.1.4 Capacitors bloated or leaking
 - 4.2.1.5 Solder joints damaged or cold
 - 4.2.1.6 Circuit board burned or de-laminated
 - 4.2.1.7 Printed wire runs / Traces burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)

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6. Modifications/Upgrades

6.1 Perform any ECN or TIL upgrades if applicable.

7. Testing Process

- 7.1 Setup
 - **7.1.1** Visually inspect unit for damaged or burned substrate, runs or missing components.

7.2 Testing Procedure

- **7.2.1** Using proper schematics verify all components for proper resistance, capacitance, range and tolerance.
- **7.2.2** Verify board to component continuity to all lands and runs.
- **7.2.3** Replace any components that do not fall within specifications or have any signs of damage.
- **7.2.4** If unit has any run or land damage, repair if possible and retest.
- 7.3 Post Testing Burn-in Required ____ Yes ___ No

 Note: All MARK I, II, & III Turbine related cards require a post testing burn-in of 100 hours.
 - **7.3.1** Apply BUS or Operational power to the card for a period of 100 hours.
 - **7.3.2** Re-test card while warm using the above procedure.

7.4 ***TEST COMPLETE ***

- 8. Notes
 - 8.1 None at this time?
- 9. Attachments
 - **9.1** None at this time?